

30V Transient Voltage Suppressor

Features

- 6270 Watts Peak Power ($t_p = 8/20\mu s$)
- Excellent Clamping Voltage
- Working Voltage: 30 V
- Low Leakage Current
- Solid-state silicon technology

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 165A (8/20 μs)

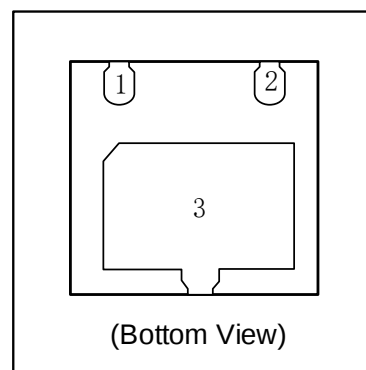
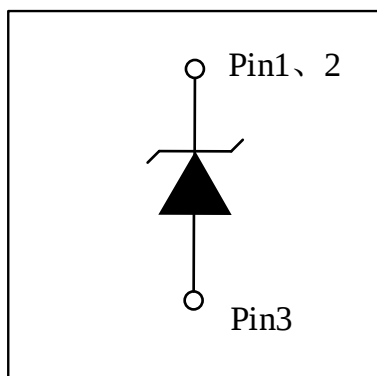
Mechanical Characteristics

- DFN2020-3L package
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant & HF
- Device meets MSL1 requirement

Applications

- Power lines
- Industrial Electronics
- Microcontroller Input Protections
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration



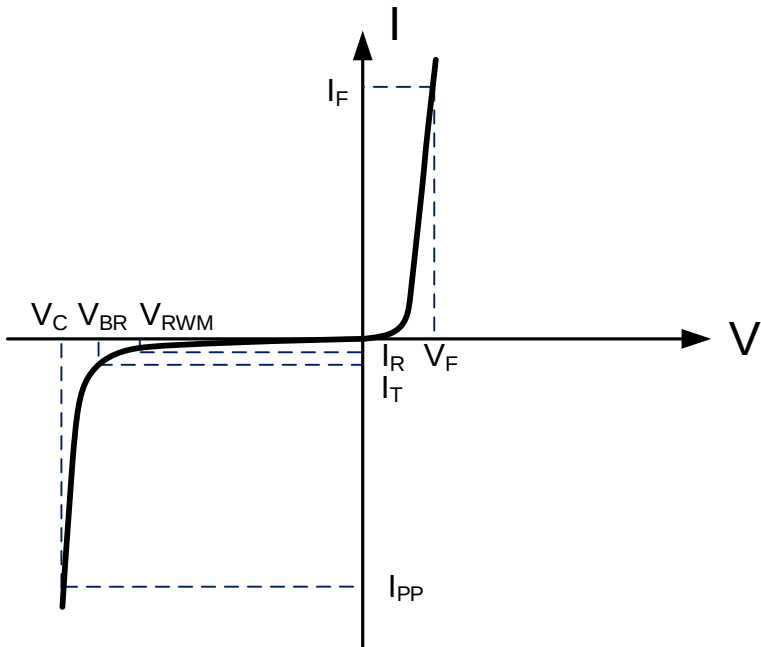
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Absolute Maximum Rating

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	6270	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	165	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



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Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}				30	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1\text{mA}$	31			V
Reverse Leakage Current	I_R	$V_{RWM}=30\text{V}$			500	nA
Forward Voltage	V_F	$I_F=10\text{mA}$	0.6		1.2	V
Clamping Voltage ⁽¹⁾	V_C	$I_{PP}=165\text{A}$, $t_p=8/20\mu\text{s}$		36	38	V
ESD Clamping Voltage ⁽²⁾	V_C	$I_{PP} = 4\text{A}$ $t_p = 0.2/100\text{ns}$		33		V
ESD Clamping Voltage ⁽²⁾	V_C	$I_{PP} = 16\text{A}$ $t_p = 0.2/100\text{ns}$		35		V
Dynamic Resistance ^{(2) (3)}	R_{DYN}	$TLP=0.2/100\text{ns}$		0.16		Ω
Junction Capacitance	C_j	$V_R = 0\text{V}$, $f = 1\text{MHz}$		540	650	pF

Note1. Measured from pin 1& pin 2 to pin 3;

Note2. TLP Setting: $t_p=100\text{ns}$, $t_r=0.2\text{ns}$, I_{TLP} and V_{TLP} sample window: $t_1=70\text{ns}$ to $t_2=90\text{ns}$.

Note3. Dynamic resistance calculated from $I_{PP}=4\text{A}$ to $I_{PP}=16\text{A}$ using “Best Fit”.

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Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

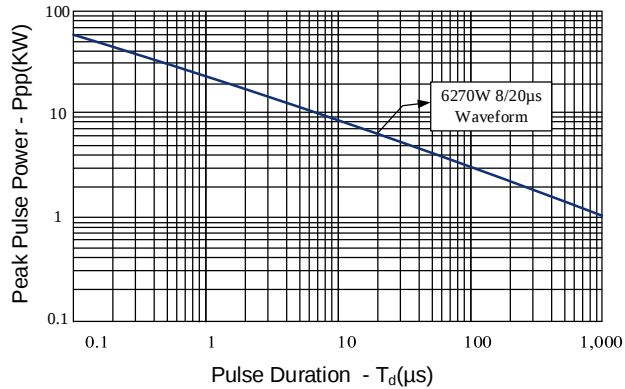


Figure 2: Power Derating Curve

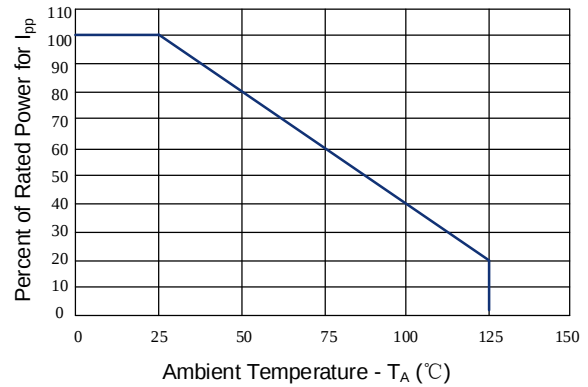


Figure 3: Clamping Voltage vs. Peak Pulse Current

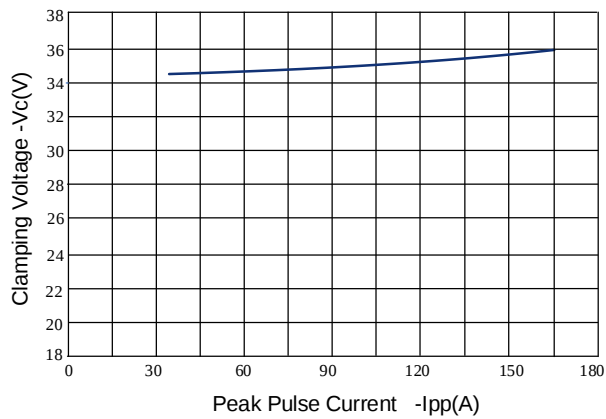


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

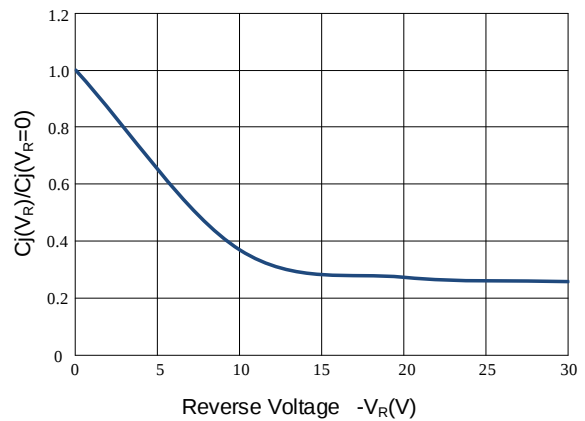


Figure 5: 8/20μs Pulse Waveform

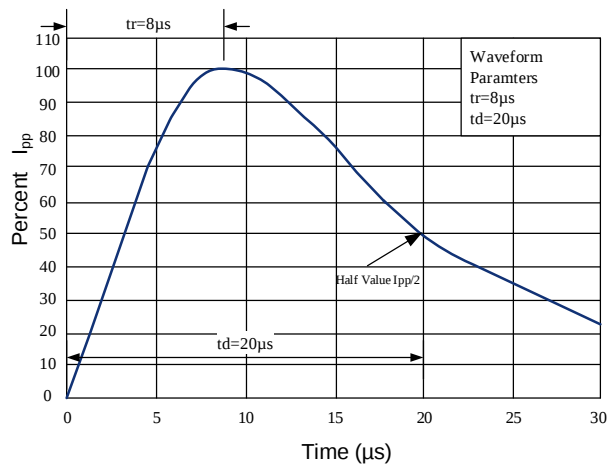
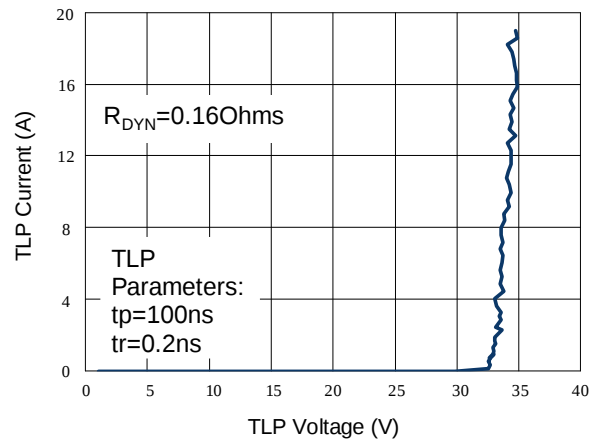


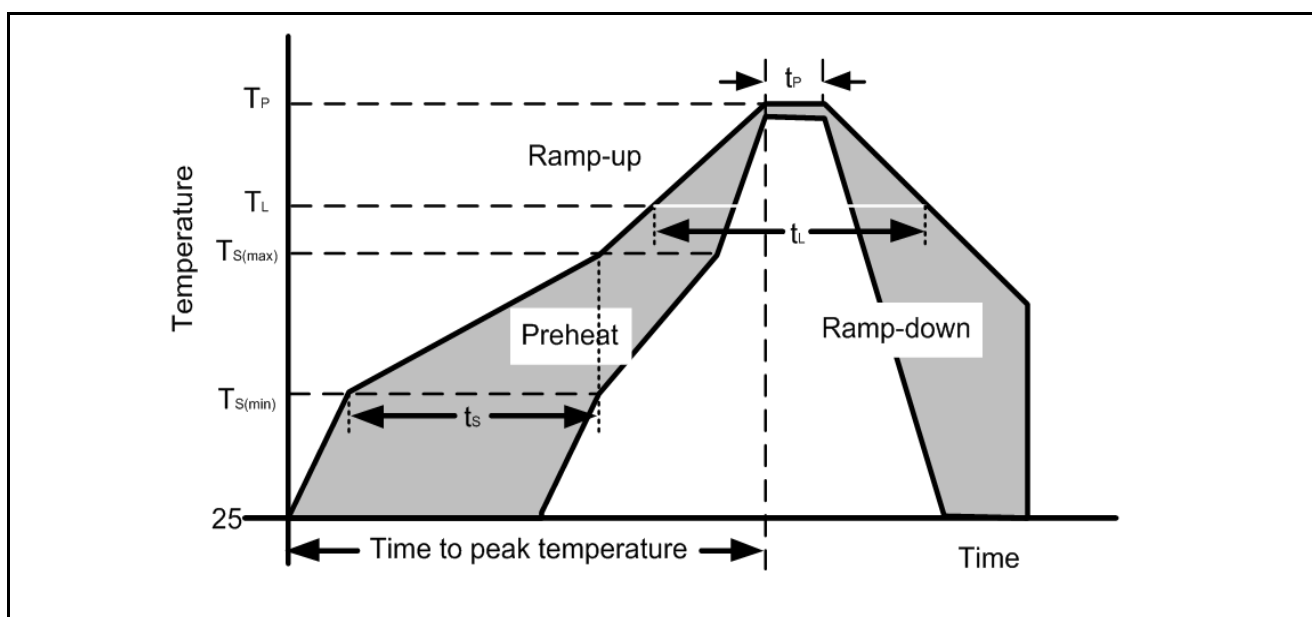
Figure 6: TLP I-V Curve



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Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_P)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



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Package Dimension

PACKAGE OUTLINE

The package outline drawings include:

- TOP VIEW:** Shows a rectangular package with dimensions D (total width), 3 (width of the central area), and E (total height). A laser mark is indicated near the bottom left corner, labeled PIN1.
- BOTTOM VIEW:** Shows the underside of the package with dimensions L1, L, E3, E2, K, b1, b, e, D2, h, and 1. It also shows the positions of the mounting pads.
- SIDE VIEW:** Shows the profile of the package with dimensions A1, A, and C1.

DFN2020-3L

SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
b	0.25	0.30	0.35
b1	0.20REF		
c	0.152REF		
D	1.90	2.00	2.10
D2	1.40	1.50	1.60
e	1.30BSC		
E	1.90	2.00	2.10
E2	0.95	1.05	1.15
E3	0.20	0.30	0.40
L	0.35	0.40	0.45
L1	0.20	0.25	0.30
h	0.20REF		
K	0.20	0.30	0.40

Notes:
Controlling Dimension: Millimeter.

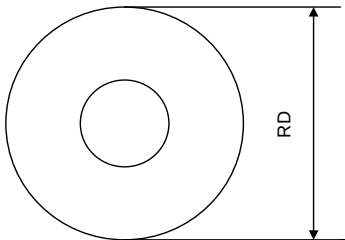
MOUNTING PAD

The mounting pad dimensions show a central pad with a width of 1.8 mm and a height of 1.2 mm. The distance between the center of the central pad and the center of each side pad is 1.3 mm. The side pads have a width of 0.5 mm and a height of 0.5 mm. The total width of the mounting area is 1.8 mm + 2 * 0.5 mm = 2.8 mm. The total height of the mounting area is 1.2 mm + 2 * 0.5 mm = 2.2 mm.

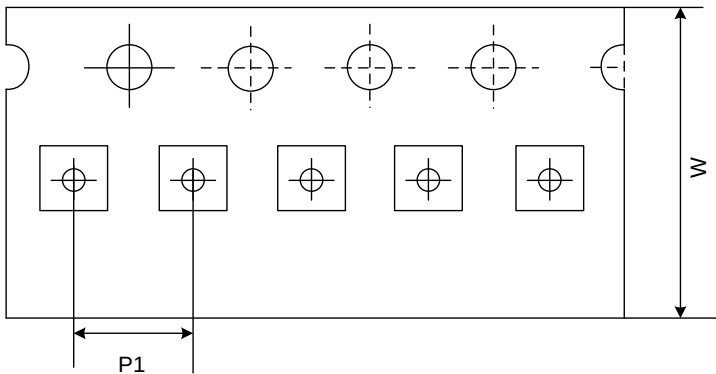
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Tape And Reel Information

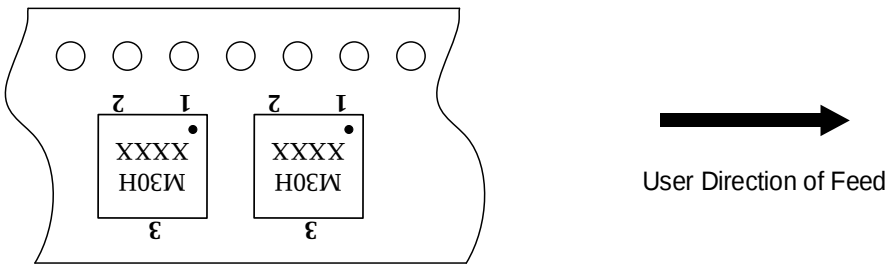
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimensions	7 inch
W	Overall width of the carrier tape	8 mm
P1	Pitch between successive cavity centers	4mm

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Ordering Information

Part	Package	Marking	Packing Information
ES30P4N3LX	DFN2020-3L	3 M30H XXXX 12 M30H=Specific Device Code XXXX=Lot Code	3k/Reel

Revision History and Checking Table

No.	Version	Date	Revision Item	Request	Function & Spec Checking	Package Checking	Tape Checking
1	1.0	2023-03-12	Released Version	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying
2	1.1	2023-04-11	Update A dimension	Wang Peng	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying